

COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Gate Threshold Voltage V<sub>GS(th)</sub> <1V</li>
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 2)
- ESD Protected Gate to 2.5kV HBM
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 7
- Ordering Information: See Page 7
- Weight: 0.006 grams (approximate)



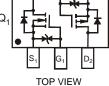
ESD PROTECTED TO 2.5kV HBM



TOP VIEW

BOTTOM VIEW

SOT-563



Q,

Internal Schematic

#### **Maximum Ratings N-CHANNEL – Q\_1** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V <sub>DSS</sub>	20	V
Gate-Source Voltage	V <sub>GSS</sub>	±6	V
Drain Current (Note 1) $T_A = 2$ $T_A = 8$	25°C I <sub>D</sub>	870 630	mA

## Maximum Ratings P-CHANNEL – $Q_2$ @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V <sub>DSS</sub>	-20	V
Gate-Source Voltage	V <sub>GSS</sub>	±6	V
Drain Current (Note 1) $T_A = 25$ $T_A = 85$		-640 -460	mA

### Thermal Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	PD	530	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ ext{ heta}JA}$	235	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 1. Device mounted on FR-4 PCB.

2. No purposefully added lead.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.



Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	100	nA	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	± 1.0	μA	$V_{GS} = \pm 4.5 V$ , $V_{DS} = 0 V$
ON CHARACTERISTICS (Note 4)						·
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5		1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>		0.3 0.4 0.5	0.4 0.5 0.7	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>	_	1.4	_	S	$V_{DS} = 10V, I_{D} = 400mA$
Diode Forward Voltage (Note 4)	V <sub>SD</sub>	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 150mA$
DYNAMIC CHARACTERISTICS			_			_
Input Capacitance	Ciss	_	60.67	_	pF	
Output Capacitance	C <sub>oss</sub>	_	9.68	—	pF	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	5.37	—	pF	
Total Gate Charge	Qg	_	736.6	_		
Gate-Source Charge	Q <sub>gs</sub>	_	93.6	_	рС	$V_{GS} = 4.5V, V_{DS} = 10V,$ In = 250mA
Gate-Drain Charge	Q <sub>gd</sub>	—	116.6	_		ID = 230IIIA
Turn-On Delay Time	t <sub>d(on)</sub>	_	5.1	_		
Turn-On Rise Time	tr	_	7.4	_	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_{L} = 47\Omega, R_{G} = 10\Omega,$
Turn-Off Delay Time	t <sub>d(off)</sub>	_	26.7	—	115	$R_L = 4752, R_G = 1052,$ $I_D = 200 \text{mA}$
Turn-Off Fall Time	t <sub>f</sub>	_	12.3	_		

# Electrical Characteristics P-CHANNEL – $Q_2$ @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$V_{GS} = 0V, I_D = -250 \mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-100	nA	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	± 2.0	μA	$V_{GS} = \pm 4.5 V$ , $V_{DS} = 0 V$
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.5	_	-1.0	V	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$
Static Drain-Source On-Resistance	D	_	0.5 0.7	0.7 0.9	Ω	$V_{GS} = -4.5V, I_D = -430mA$
	R <sub>DS (ON)</sub>		1.0	1.3	52	$V_{GS} = -2.5V, I_D = -300mA$ $V_{GS} = -1.8V, I_D = -150mA$
Forward Transfer Admittance	Y <sub>fs</sub>	_	-0.9	_	S	$V_{DS} = 10V, I_{D} = -250mA$
Diode Forward Voltage (Note 4)	V <sub>SD</sub>	_	-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -150mA$
DYNAMIC CHARACTERISTICS						_
Input Capacitance	C <sub>iss</sub>	_	59.76	_	pF	
Output Capacitance	C <sub>oss</sub>	_	12.07	—	pF	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	6.36	—	pF	
Total Gate Charge	Qg	_	622.4	—		
Gate-Source Charge	Q <sub>gs</sub>	_	100.3		рС	$V_{GS} = -4.5V, V_{DS} = -10V,$ ID = -250mA
Gate-Drain Charge	Q <sub>gd</sub>	_	132.2	—		ID = -230IIIA
Turn-On Delay Time	t <sub>d(on)</sub>	_	5.1	—		1/1 = -10/1/1 = -15/1
Turn-On Rise Time	tr	_	8.1	_	ns	$V_{DD} = -10V, V_{GS} = -4.5V,$ $R_1 = 47\Omega, R_G = 10\Omega,$
Turn-Off Delay Time	t <sub>d(off)</sub>		28.4	—	113	$I_{D} = -200 \text{mA}$
Turn-Off Fall Time	t <sub>f</sub>	—	20.7			

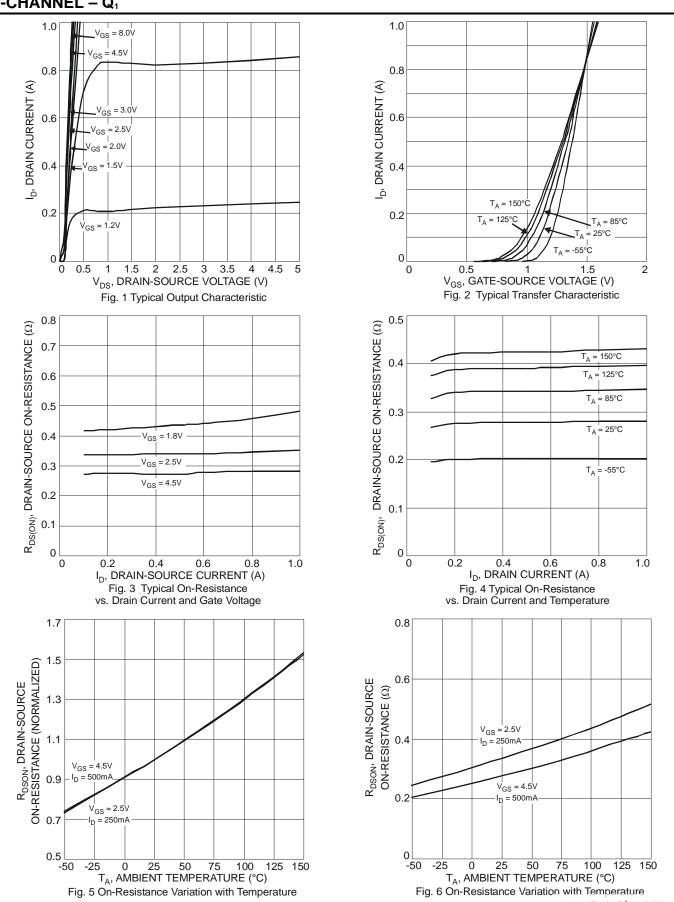
Notes: 4. Short duration pulse test used to minimize self-heating effect.

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## N-CHANNEL – Q<sub>1</sub>



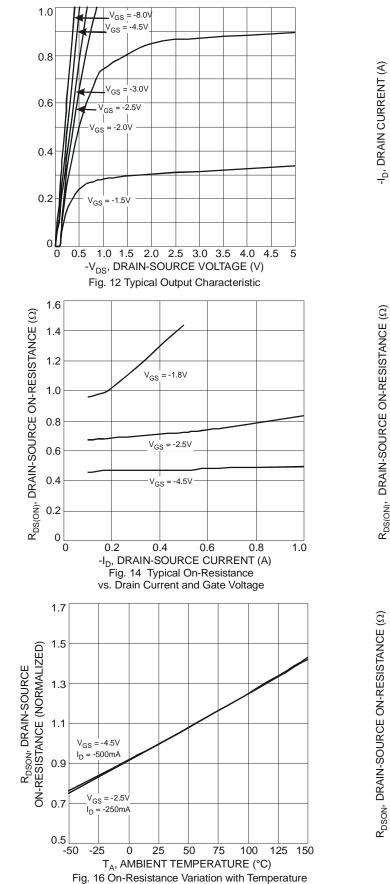
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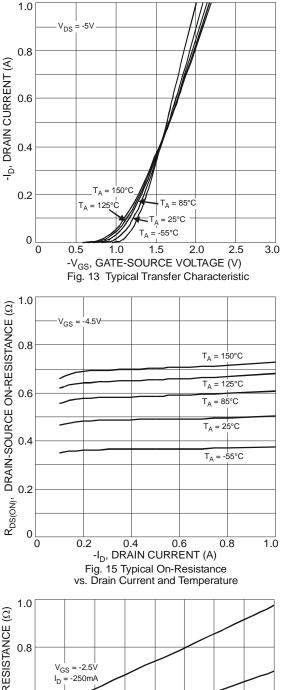


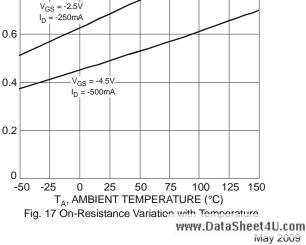
#### N-CHANNEL – Q1 (continued) 1.6 1.0 $V_{\text{GS(TH)}},$ GATE THRESHOLD VOLTAGE (V) 0.8 1.2 I<sub>S</sub>, SOURCE CURRENT (A) T<sub>A</sub> = 25°C 0.6 0.8 1mA I<sub>D</sub> 0.4 = 250µA 0.4 0.2 0 0 0.4 0.6 0.8 1.0 V<sub>SD</sub>, SOURCE-DRAIN VOLTAGE (V) -50 -25 0 25 50 75 100 125 150 0.2 1.2 T<sub>A</sub>, AMBIENT TEMPERATURE (°C) Fig. 7 Gate Threshold Variation vs. Ambient Temperature Fig. 8 Diode Forward Voltage vs. Current 100 1,000 T<sub>A</sub> = 150°C С I<sub>DSS</sub>, LEAKAGE CURRENT (nA) C, CAPACITANCE (pF) $T_A = 125^{\circ}C$ 100 10 Coss $T_A = 85^{\circ}C$ -C<sub>rss</sub> 10 $T_A = 25^{\circ}C$ 1 1 0 5 10 15 20 8 12 16 20 0 4 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) Fig. 9 Typical Total Capacitance Fig. 10 Typical Leakage Current vs. Drain-Source Voltage 1 r(t), TRANSIENT THERMAL RESISTANCE D = 0.7. . . . . . . D = 0.5 D = 0.30.1 D = 0.1 0.9 D = 0.05 $\begin{aligned} \mathsf{R}_{\theta \mathsf{J}\mathsf{A}}(t) &= \mathsf{r}(t) \,^* \, \mathsf{R}_{\theta \mathsf{J}\mathsf{A}} \\ \mathsf{R}_{\theta \mathsf{J}\mathsf{A}} &= 260^\circ \mathrm{C/W} \end{aligned}$ D = 0.020.01 P(pk) D = 0.01 t<sub>2</sub> 0.005 $T_J - T_A = P * R_{\theta JA}(t)$ Duty Cycle, $D = t_1/t_2$ D = Single Pulse 0.001 0.00001 0.0001 0.001 0.01 0.1 10 100 1,000 1 t1, PULSE DURATION TIME (s) Fig. 11 Transient Thermal Response



#### P-CHANNEL – Q<sub>2</sub>





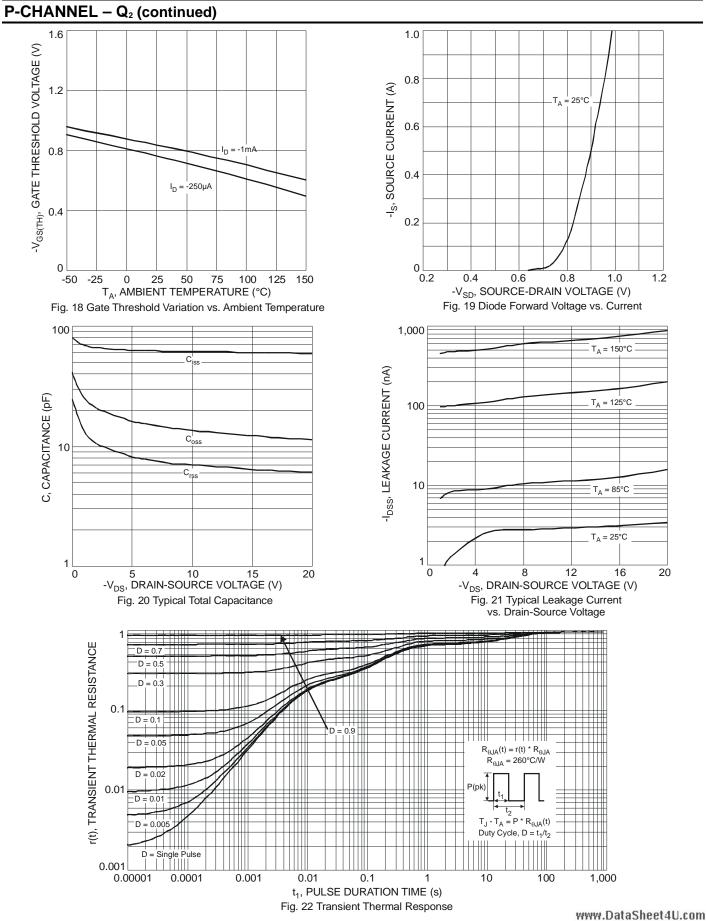


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6 of 8 www.diodes.com

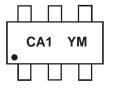


## Ordering Information (Note 5)

Part Number	Case	Packaging
DMG1016V-7	SOT-563	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**

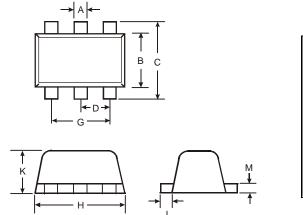


CA1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: W = 2009) M = Month (ex: 9 = September)

Date Code Key

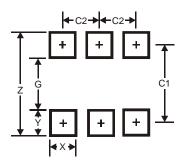
Year	200	9	2010		2011	20	12	2013		2014	2	2015
Code	W		Х		Y		Ζ	А		В		С
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

## **Package Outline Dimensions**



SOT-563							
Dim	Min	Min Max 1					
Α	0.15	0.30	0.20				
В	1.10	1.25	1.20				
С	<b>C</b> 1.55 1.70 1.6						
D	-	-	0.50				
G	0.90	1.10	1.00				
Н	1.60						
Κ	0.55	0.60	0.60				
L	0.10	0.30	0.20				
Μ	0.10	0.18	0.11				
All	Dimens	sions in	mm				

# Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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